Roll No:

Subject Code: AMTVL0112

NOIDA INSTITUTE OF ENGINEERING AND TECHNOLOGY, GREATER NOIDA

(An Autonomous Institute Affiliated to AKTU, Lucknow)

MASTER OF TECHNOLOGY (M.Tech)

(SEM: FIRST; Theory Examination (2020-2021)

SUBJECT NAME: MOS DEVICE MODELLING

Time: 3Hours

Max. Marks: 70

General Instructions:

1.

- > All questions are compulsory. Answers should be brief and to the point.
- ▶ This Question paper consists of ...02...pages & ...08......questions.
- > It comprises of three Sections, A, B, and C. You are to attempt all the sections.
- Section A -Question No- 1 is objective type questions carrying 1 mark each, Question No- 2 is very short answer type carrying 2 mark each. You are expected to answer them as directed.
- Section B Question No-3 is Long answer type -I question with external choice carrying 4marks each. You need to attempt any five out of seven questions given.
- Section C -Question No. 4-8 are Long answer type II (within unit choice) questions carrying 7marks each. You need to attempt any one part <u>a or b.</u>
- Students are instructed to cross the blank sheets before handing over the answer sheet to the invigilator.
- ▶ No sheet should be left blank. Any written material after a blank sheet will not be evaluated/checked.

SECTION -A

Attempt all parts-		[5x1=5]	CO
a.	In ratioed logic the entire pull-up-network is replaced by? (1) single unconditional load (2) Nothing (3) Pull down network (4) All of the above	(1)	CO2
b.	 What are the techniques to reduce the switching activity factor? (1) Logic restructuring (2) Input ordering (3) Time multiplexing (4) All of the above 	(1)	CO1
c.	Statement: Sizing is only effective when the load is dominated by the fan-out. Is the given statement true or false? (1) True (2) False	(1)	CO2
d.	 Which type of MOSFET structure is best for high performance application? (1) PD SOI (2) FD SOI (3) FinFet (4) NCFET 	(1)	CO4
e.	How lambda λ can be represented in VLSI design?	(1)	CO4

[5x2=10]

	a.	What is the need of Layouts?	(2)	CO1
	b.	What is photolithography?	(2)	CO2
	c.	Which is better from NAND and NOR logic gates? Justify your answer.	(2)	CO2
	d.	Define constant voltage scaling of MOS device.	(2)	CO3
	e.	Why selection of W/L ratio of a MOS device is critical?	(2)	CO5
		SECTION -B		
3.	Ans	swer any <u>five</u> of the following-	[5x4=20]	CO
	a.	Explain the I-V characteristics of FinFET device and compare it with n-channel enhancement type MOSFET. Also, derive the mathematical relationship for the drain current.	(4)	CO4
	b.	How velocity saturated MOS models are different from normal long channel MOS models?	(4)	CO3
	c.	Consider an n channel MOSFET with following characteristics: $t_{ox}=10$ nm, $\mu_n=520$ cm ² /V-s, (W/L)=8, $V_{Tn}=+0.70$ V, $V_{gsn}=2$ V and $V_{dsn}=2$ V. Find the drain source current.	(4)	CO5
	d.	What is pass transistor logic? Why it is preferred over NMOS/PMOS switch?	(4)	CO2
	e.	Explain, how VTC of CMOS inverter is impacted the device aspect ratio?	(4)	CO4
	f.	Explain about non ideal effects in a MOS device.	(4)	CO3
	g.	Define the latch up problem in CMOS and explain how it can be avoided.	(4)	CO2
	_	SECTION-C		
4.	An	swer any <u>one of</u> the following-	[5x7=35]	
4.		swer any <u>one</u> of the following- Describe twin tub process for fabrication of the CMOS transistor with suitable diagram.	[5x7=35] (7)	CO2
4.	a.	Describe twin tub process for fabrication of the CMOS transistor with suitable		CO2 CO5
4. 5.	a. b.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram.	(7)	
	a. b. Ar	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs.	(7)	
	a. b. Ar a.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs.	(7) (7)	CO5
	a. b. Ar a. b.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. nswer any <u>one of the following-</u> Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of	(7)(7)(7)	CO5 CO3
5.	a. b. Ar a. b.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. The swer any <u>one of the following-</u> Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS.	(7)(7)(7)	CO5 CO3
5.	a. b. Ar a. b. Ans a	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. Inswer any <u>one of the following-</u> Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any <u>one of the following-</u> Define impact ionization in MOS model and how scaling impacts the vertical	 (7) (7) (7) (7) (7) 	CO5 CO3 CO2
5.	a. b. Ar a. b. Ans a b.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. nswer any <u>one of the following-</u> Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any <u>one of the following-</u> Define impact ionization in MOS model and how scaling impacts the vertical and horizontal electric field?	 (7) (7) (7) (7) (7) (7) 	CO5 CO3 CO2 CO2
5. 6.	a. b. Ar a. b. Ans a b. Ans	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. Inswer any <u>one of the following-</u> Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any <u>one of the following-</u> Define impact ionization in MOS model and how scaling impacts the vertical and horizontal electric field? Derive the threshold model with and without body bias.	 (7) (7) (7) (7) (7) (7) 	CO5 CO3 CO2 CO2
5. 6.	a. b. Ar b. Ans a b. Ans a.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. Inswer any <u>one</u> of the following- Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any <u>one</u> of the following- Define impact ionization in MOS model and how scaling impacts the vertical and horizontal electric field? Derive the threshold model with and without body bias. Swer any <u>one</u> of the following- Make a comparison between MOS Model level1,2,3 with the help of	 (7) (7) (7) (7) (7) (7) (7) 	CO5 CO3 CO2 CO2 CO2
5. 6.	a. b. Ar b. Ans a b. Ans a.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. Inswer any <u>one</u> of the following- Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any <u>one</u> of the following- Define impact ionization in MOS model and how scaling impacts the vertical and horizontal electric field? Derive the threshold model with and without body bias. Swer any <u>one</u> of the following- Make a comparison between MOS Model level1,2,3 with the help of mathematical models. Write a SPICE program for a NAND gate and define all global signals in the	 (7) 	CO5 CO3 CO2 CO2 CO2 CO5
5. 6. 7.	a. b. Ar b. Ans a b. Ans a. b.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. Inswer any one of the following- Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any one of the following- Define impact ionization in MOS model and how scaling impacts the vertical and horizontal electric field? Derive the threshold model with and without body bias. Swer any one of the following- Make a comparison between MOS Model level1,2,3 with the help of mathematical models. Write a SPICE program for a NAND gate and define all global signals in the design. Answer any one of the following- Draw a neat energy band diagrams for n-MOSFET and FINFET device.	 (7) 	CO5 CO3 CO2 CO2 CO2 CO5
5. 6. 7.	a. b. Ar b. Ans a b. Ans a. b.	Describe twin tub process for fabrication of the CMOS transistor with suitable diagram. Explain the second order effects in MOSFETs. Inswer any one of the following- Define and derive the switching inverter delay for a CMOS configuration. Explain how short channel and narrow width impacts the design performance of CMOS. Swer any one of the following- Define impact ionization in MOS model and how scaling impacts the vertical and horizontal electric field? Derive the threshold model with and without body bias. Swer any one of the following- Make a comparison between MOS Model level1,2,3 with the help of mathematical models. Write a SPICE program for a NAND gate and define all global signals in the design. Answer any <u>one</u> of the following-	 (7) 	CO5 CO2 CO2 CO2 CO5 CO5

Attempt <u>all</u> parts-

2.